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PRODUCT CHANGE NOTIFICATION

PCN: PCN145356

Date: December 24, 2014

Subject: Qualification of New Pure Tin Lead Frame and New Mold Compound for Select 40-Lead QFN Packages Assembled at ASE Taiwan

To: PCN ADMIN
CYPRESS
pcn_admin@cypress.com

Change Type: Minor

Description of Change:

Cypress announces the qualification of new pure Tin (matte Sn) lead frame and new mold compound for 40-Lead QFN stacked die 6x6x1 mm packages at ASE Kaohsiung, Taiwan. These changes have been done to improve the process control resulting in better product quality, field reliability and continuity of supply. This in turn provides the means for Cypress to continue to meet our customers' requirements and meet our delivery commitments in dynamic market conditions.

| Material | New Bill of Materials | Current Bill of Materials |
|-----------------|-----------------------|---------------------------|
| Mold Compound | Sumitomo EME-G700LA | Sumitomo EME-G631H |
| Die Attach Film | Hitachi FH 900 | Hitachi FH 900 |
| Bond Wire | 0.8 mil Au | 0.8 mil Au |
| Lead Finish | Pure matte Sn | Ni/Pd/Au |

Part Numbers Affected: 9

Affected Parts: Please refer to the attached 'Affected parts list' file

Qualification Status:

The new lead frame and new mold compound material have been qualified through a series of tests documented in Qualification Test Plan (QTP) 135103. The qualification report can be found as an attachment to this notification or by visiting www.cypress.com and typing the QTP number in the keyword search window.

Sample Status:

Qualification samples are not built ahead of time for all part numbers affected by this change. Please review the attached file for a list of affected part numbers with their associated sample ordering part numbers. Sample requests for products without sample order part numbers are not built ahead of time, will be built to order and subject to standard lead times. Please contact your sales representative as soon as possible, but within 30 days of the date of this PCN, to place any sample orders.

Approximate Implementation Date:

Effective 90 days from the date of this notification or upon customer approval, whichever comes first, Cypress will transition to shipments of the affected part numbers with the newly qualified lead frame and mold compound material.

Anticipated Impact:

None anticipated. Products manufactured with the new lead frame and new mold compound material are completely compatible with existing product from a functional, parametric, and quality performance perspective.

Cypress also recommends that customers take this opportunity to review these changes against current application notes, system design considerations and customer environment conditions to assess impact (if any) to their application.

Method of Identification:

Cypress maintains traceability of product to wafer level, including wafer fabrication and assembly location, through the lot number marked on the package. There will be no changes to the ordering codes or marking on production material shipped after the change implementation date.

Response Required:

No response is required.

For additional information regarding this change, contact your local sales representative or contact the PCN Administrator at pcn_adm@cypress.com.

Sincerely,

Cypress PCN Administration